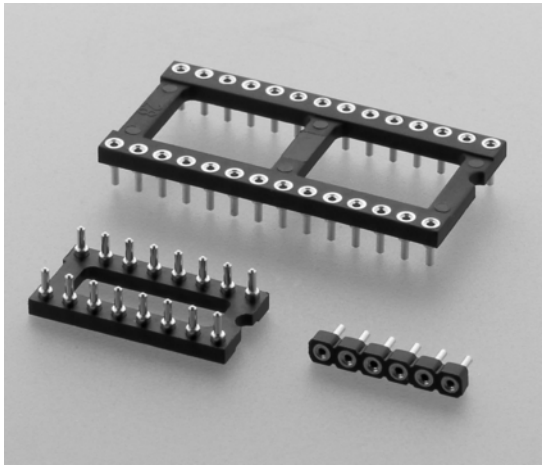
172 / 186

Ultra flache IC-Fassungen / IC-Leisten RM 2,54mm, BH 2,4mm

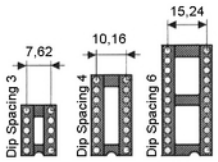
Ultra Flat IC Sockets / IC Headers, 2.54mm Pitch, 2.4mm Profile

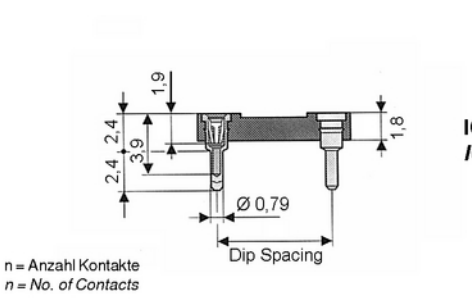
Technische Daten / *Technical Data*

Isolierkörper	Thermoplastischer Kunststoff, nach UL94 V-0
Insulator	*Thermoplastic, rated UL94 V-0*
Kontaktmaterial	Hülse: Messing gedreht Feder: 4-Lamellen-Clip, Beryllium-Kupfer
Contact Material	*Sleeve: screw machined brass* *Clip: 4-Finger-Clip, Beryllium-Copper*
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni (2 ... 3µm)
Contact Surface	*Acc. to options (see below), over Ni (2 ... 3µm)*
Lötbarkeit	IEC 60512-12A
Solderability	*IEC 60512-12A*
Durchgangswiderstand	< 10mΩ
Contact Resistance	*< 10mΩ*
Isolationswiderstand	> 1000MΩ
Insulation Resistance	*> 1000MΩ*
Spannungsfestigkeit	$1kV_{RMS}$
Test Voltage	*$1kV_{RMS}$*
Nennspannung	$100V_{RMS}$ / $150V_{DC}$
Voltage Rating	*$100V_{RMS}$ / $150V_{DC}$*
Nennstrom	3A
Current Rating	*3A*
Temperaturbereich	-55°C ... +125°C
Temperature Range	*-55°C ... +125°C*
Verarbeitung	Wellen- oder Reflow-Lötverfahren
Processing	*Wave or reflow soldering*

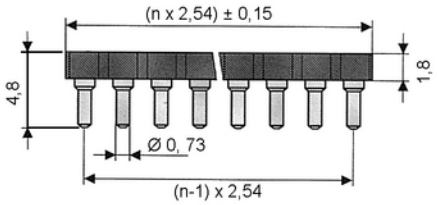


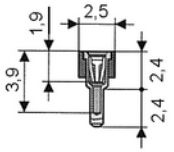
Für Rundstifte Ø0,40-0,56mm
oder Vierkantstifte 0,25x0,45mm.
For Ø0.40-0.56mm round pins
or 0.25x0.45mm rectangular pins.





IC-Fassung Serie 172
IC-Socket Series 172





IC-Leiste Serie 186
IC-Strip Series 186

Series	***Contacts****	***DIP****	***Sleeve Plating***	***Clip Plating****
172	**14**	**3**	**50**	**00**
172 IC-Fassung *IC-Socket*	**06/08/10/14/16/** **18/20/22/24/28 ==>** **3** 7,62mm **20/22/24/28=====>** **4** 10,16mm **24/28/32/36/** **40/48/50 =======>** **6** 15,24mm		**50** Verzinnt (Standard) *Tin plated (Standard)*	**00** Vergoldet (Standard) *Gold plated (Standard)* **10** Vergoldet 0,25µm *0,25µm gold plated* **30** Vergoldet 0,75µm *0,75µm gold plated*

Series	***Contacts****	***DIP***	***Sleeve Plating***	***Clip Plating****
186	**14**	**1**	**50**	**00**
186 IC-Leiste *IC-Strip*	**01-64** Einreihig *Single row*	**1** Einreihig *Single row*	**50** Verzinnt (Standard) *Tin plated (Standard)*	(siehe oben) *(see above)*

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
please replace by your specifications.

TEL +49 5223 98507-0
FAX +49 5223 98507-50

W+P PRODUCTS

E-MAIL sales@wppro.com
WEBSITE www.wppro.com

Informationen zum Reflow-Lötverfahren
Reflow Soldering Information

Reflow-Lötempfehlung
Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J_STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_S$min	150°C
Temperatur Maximum $T_S$max	200°C
Dauer $T_S$min - $T_S$max	60-180s
Temperatur Lötbereich T_L	217°C
Verweildauer oberhalb T_L	60-180s
Ramp-Up Rate $T_S$max - T_P	max. 3°C / s
Höchsttemperatur T_P	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_P$max - $T_S$min	6°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_S$min	*150°C*
Maximum Temperatur $T_S$max	*200°C*
Duration $T_S$min - $T_S$max	*60-180s*
Soldering Range Temperature T_L	*217°C*
Duration above T_L	*60-180s*
Ramp-Up Rate $T_S$max - T_P	*max. 3°C / s*
Peak Temperature T_P	*260°C ±5*
Duration Peak Temperature	*20-40s*
Ramp-Down Rate $T_P$max - $T_S$min	*6°C / s*
Duration 25°C - Peak Temp. T_P	*Max. 8min*